1		3	4	. 5		6	7		8		
. 1		•		RECOMMENDA	TION FOR	SOLDER PROCESS	ING	'			
	har-flex angled male connector c Sus RoHS√										
				Solder paste recommendation  The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb40  DCR and plating							
ļ											
ļ	GENERAL INFORMATION		PCB pad plating  The har flow composters are colderable on load free pad surfaces like HAL NiAu Immersion Sp.								
	No. of contacts	ontacts from 6 to 100poles, all even numbers				The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn.					
-	Contact spacing 1,27mm x 1,27mm [0,050"x0,050"]			Stencil recommendation							
	Test Voltage	500V < 25 mOhm		The solder deposition has to be placed on the pad area of the contact solder tines.  Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads.  The size of the solder stencil apertures is depending on the thickness of the stencil.							
	Contact resistance										
	Insulation resistance	≥ 10x10^9Ω		In general, the thinner stencils will need larger apertures to result in the required volume of solder paste.							
3	Working current acc. to IEC 60512, at 70°C, 80% derating	see derating diagram -55°C +125°C	The minimum required solder paste volume for the signal pins is 0,077mm³, for the hold down it is 0,39mm³.  For example, this can be achieved with the following stencil data:								
	Working temperature range Termination technology	SMT	For example, t								
	Reflow processing temperature	min. 150s >217°C		Stencil ti	hioknooo	PCB pad size	Signal pins proposal stencil aperture size	andoulated as	older paste volume		
	(acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 30s > 240°C		I —	) µm	0,8 x 0,8 mm	0,72 x 0,72 mm	+	078 mm <sup>3</sup>		
	Clearance & creepage distance	arance & creepage distance 0,4mm min.			<i>γ</i> μιτι	0,0 x 0,0 111111	0,72 X 0,72 IIIII		57 O 111111		
	Insertion force (depending on mating connector)	approximately 0,5N/contact					Hold-downs				
	Withdrawal force (depending on mating connector)	approximately 0,5N/contact		Stencil t	hickness	PCB pad size	proposal stencil aperture size	calculated so	older paste volume		
	Mating cycles	PL1 : 500 mating cycles		150	) µm	2,7 x 1,2 mm	2,43 x 1,08 mm	0,	394 mm³		
	PL2 : 250 mating cycles		If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging th								
	RoHS - compliant	Yes Yes 100V / 150V (depending on installation category)		stencil aperture. Depending on the PCB design, the solder depostion may protrude the PCB pads. But to achieve a go sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.							
	Leadfree Washington to to 150 00004.4										
	Working voltage acc. to to IEC 60664-1  UL file acc. UL 1977										
	UL file acc. CSA-C22.2 (for Canada)	ECBT2.E102079		Coplanarity of co	Coplanarity of contacts						
4	PSL level acc. ECA/IPC/JEDEC J-STD-075	ECBT8.E102079 PSL R0		All connectors are tested for coplanarity of contacts and are in the range of 6 pin to 50 pin: ≤ 0,1mm							
	MSL level acc. ECA/IPC/JEDEC J-STD-073 FSL R0  MSL level acc. ECA/IPC/JEDEC J-STD-020D MSL 1			52 pin to 68 pin: ≤ 0,12mm							
				70 pin to 80 pin: ≤ 0,13mm							
ļ	INSULATOR MATERIAL				82 pin to 100 pin: ≤ 0,15mm						
	erial LCP (liquid crystalline polymer)		Performance level								
	Color	Black		Performance level 1 (recommended for majority of applications) Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 pp							
	UL classification	UL94-V0		Measurement of c	Initial 250 mating cycles, 10 days gas test (25°C / 75% r.n.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 pp ——— Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance						
	Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)	and visual inspection.								
ſ	CONTACT MATERIAL			Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.  Part number definition: 15 2							
Ī	Contact material	material Copper alloy				2					
	Plating termination zone	Sn Au over PdNi (acc. to Performance level)		Performance level 2 Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance.							
1	<u> </u>	Au over PdNi (acc. to Performance	level)						it of confact resistanc		
ſ	Plating contact sliding side	1	level)	Measurement of c	contact resistion.	tance. The remainin	g 125 mating cycles are subject to	o measuremer			
	<u> </u>	1	level)	Measurement of c and visual inspect Visual inspection.	contact resistion. No abrasio	stance. The remaining of the contact finish		o measuremer			
-	Plating contact sliding side  DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity  The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non	A Nuclea	level)	Measurement of cand visual inspection. Visual inspection. Part number defin Performance level Defined contact si	contact resistion.  No abrasio ition: 15  I S4  urface of mi	tance. The remainin	g 125 mating cycles are subject to	o measuremer			
	Plating contact sliding side  DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity  The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.	1	(pod-160pod	Measurement of cand visual inspect Visual inspection. Part number defin  Performance level Defined contact so Part number defin  All Defined contact so Part number defin	contact resistion.  No abrasio ition: 15  I S4  urface of mi	n of the contact finish 6	g 125 mating cycles are subject to n through to the base material. No 0,7+0,2µm PdNi	Ref. Sub. Date	pairment.		
	Plating contact sliding side  DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)  The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.  Control and test procedures according to DIN IEC 60512-5	A Nuclea	Food - 1800/pcd  -1: 6 pol -5: 10 pol -6: 100/pcd	Measurement of cand visual inspect Visual inspection. Part number defin Performance level Defined contact standard part number defin  All Department Department	contact resistion.  No abrasionition: 15  I S4  urface of minition: 15  Dimensions in mal Size DIN Allers  Its reserved  EL PD	n of the contact finish 6	g 125 mating cycles are subject to through to the base material. No 0,7+0,2µm PdNi  tol.  Inspected by Standardisation HOFFMANN	Ref. Sub.	State Final Release		
=	Plating contact sliding side  DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)  The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.	Electrical load [A]	70 80 90 100 110 120 130	Measurement of cand visual inspect Visual inspection. Part number defin Performance level Defined contact standard part number defin  All Defined Contact Standard part number defined Contact Stand	contact resistion.  No abrasionition: 15  I S4  urface of minition: 15  Dimensions in mal Size DIN Allers  Its reserved  EL PD	n of the contact finish 6	g 125 mating cycles are subject to through to the base material. No 0,7+0,2µm PdNi  tol.  Inspected by Standardisation HOFFMANN	Ref. Sub. Date	pairment.  State		

